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In The Claims

Claims 14-39 are pending in the application with claims 1-13 and 40-47 canceled herein.

Claims 1-13 (canceled).

14. (original) An electronic apparatus fabrication method comprising:
forming an insulative substrate comprising an aluminum-based glass; and
forming a layer comprising a semiconductive material over the substrate.

15. (original) The method of claim 14 further comprising forming a
semiconductor device comprising at least a part of the semiconductive material layer.

16. (original) The method of claim 14 wherein the semiconductive material
layer is formed on and in contact with the insulative substrate.

17. (original) The method of claim 14 wherein forming the insulative substrate
comprises:

forming a mixture of a powder comprising aluminum, a powder comprising
silicon, and a powder comprising carbon;

mechanically activating the mixture and allowing the mixture to react by
spontaneous ignition; and

forming the reacted mixture into a plate.

18. (original) The method of claim 17 wherein allowing the mixture to react
comprises exposing the mixture to air.

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19. (original) The method of claim 17 wherein allowing the mixture to react comprises exposing the mixture to oxygen gas and to an inert gas excluding nitrogen.

20. (original) The method of claim 14 wherein the insulative substrate exhibits a CTE sufficiently close to a CTE of the semiconductive material layer such that a strain of less than 1% would exist between a 1000 Å thickness of the semiconductive material layer and the insulative substrate.

21. (original) The method of claim 20 wherein the semiconductive material layer has a thickness of about 1000 Å or less.

22. (original) The method of claim 20 wherein the strain would be less than 0.6%.

23. (original) The method of claim 14 wherein forming the semiconductive material layer comprises:

removing a layer of silicon from a monocrystalline silicon wafer; and
bonding the silicon layer to the insulative substrate.

24. (original) The method of claim 23 wherein removing the layer of silicon comprises implanting ions into the wafer.

25. (original) The method of claim 23 wherein bonding the silicon layer comprises heating to at least 400 °C.

26. (original) The method of claim 23 wherein bonding the silicon layer comprises laser assisted annealing.

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27. (original) The method of claim 23 wherein bonding the silicon layer comprises activating a surface of at least the silicon wafer by exposure to a plasma.

28. (original) The method of claim 14 further comprising chemically-mechanically polishing the semiconductive material layer.

29. (original) A silicon-on-insulator integrated circuit fabrication method comprising:

forming a mixture of a powder comprising aluminum, a powder comprising silicon, and a powder comprising carbon;

mechanically activating the mixture and allowing the mixture to react by spontaneous ignition;

forming the reacted mixture into a glass substrate comprising aluminum oxycarbide;

removing a layer of silicon from a monocrystalline silicon wafer;

bonding the silicon layer on and in contact with the glass substrate; and

forming a semiconductor device comprising at least a part of the silicon layer.

30. (original) The method of claim 29 wherein the glass substrate further comprises aluminum carbide, silicon carbide, and α -alumina.

31. (original) The method of claim 29 wherein allowing the mixture to react comprises exposing the mixture to air.

32. (original) The method of claim 29 wherein allowing the mixture to react comprises exposing the mixture to oxygen gas and an inert gas that does not comprise nitrogen.

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33. (original) The method of claim 29 wherein the glass substrate exhibits a CTE sufficiently close to a CTE of the silicon layer such that a strain of less than 1% would exist between a 1000 Å thickness of the silicon layer and the glass substrate.

34. (original) The method of claim 33 wherein the silicon layer has a thickness of about 1000 Å or less.

35. (original) The method of claim 33 wherein the strain would be less than 0.6%.

36. (original) The method of claim 29 wherein removing the layer of silicon comprises implanting ions into the wafer.

37. (original) The method of claim 29 wherein bonding the silicon layer comprises heating to at least 400 °C.

38. (original) The method of claim 29 wherein bonding the silicon layer comprises laser assisted annealing.

39. (original) The method of claim 29 further comprising chemically-mechanically polishing the silicon layer after bonding to the glass substrate.

Claims 40-47 (canceled).